



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Philip A. Rochette

PATENT APPLICATION

Serial No.: 10/817,619

Group Art Unit: 2811

Filed: April 1, 2004

Examiner:

For: METHOD AND APPARATUS TO ELIMINATE GALVANIC
CORROSION ON COPPER DOPED ALUMINUM BOND PADS
ON INTEGRATED CIRCUITS

Supplemental Information Disclosure Statement

Hon. Commissioner for Patents
Alexandria, VA 22313

Sir:

The following information is submitted in
compliance with Applicant's duty of disclosure under 37
CFR § 1.56. A copy of each reference is enclosed.

Other References

S. Thomas et al., "Micro-Corrosion of Al-Cu
Bonding Pads", IEEE Transactions on Components, Hybrids,
and Manufacturing Technology, June 1987, Vol. CHMT-10,
No. 2, pp. 252-257.

Printout: "Galvanic Voids, Semiconductor
Reliability News, April 1992, 1 page.

CERTIFICATE OF MAILING


I hereby certify that this paper (along with
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Signed: *Sally Azevedo*
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Date: June 30, 2004

Respectfully submitted,

Thomas Schneck

Thomas Schneck
Reg. No. 24,518
P.O. Box 2-E
San Jose, CA 95109-0005
(408) 297-9733

FORM PTO-1449			Atty. Docket No. ATM-302		Serial No. 10/817,619	
LIST OF PRIOR ART CITED BY APPLICANT			<div style="display: flex; justify-content: space-between;"> <div style="width: 45%;">  </div> <div style="width: 50%;"> Applicant: Philip A. Rochette </div> </div> <div style="display: flex; justify-content: space-between; margin-top: 10px;"> <div style="width: 45%;"> Filing Date: April 1, 2004 </div> <div style="width: 50%;"> Group: 2811 </div> </div>			
U.S. PATENT DOCUMENTS						
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OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)						
AM	S. Thomas et al., "Micro-Corrosion of Al-Cu Bonding Pads", IEEE Transactions on Components, Hybrids, and Manufacturing Technology, June 1987, Vol. CHMT-10, No. 2, pp. 252-257.					
AN	Printout: "Galvanic Voids, Semiconductor Reliability News, April 1992, 1 page.					
AO						
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<p>*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>						